



Conceptual Design Study of a 40⁺ T ReBCO Solenoid for the MUON Collider

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Reference Conductor for the study 1/2

<Schematic of RE-based HTS tape>

50 um

[EuBCO+BHO] 2.5 µm

Stabilizer [Cu plating] 20µm Protection layer [Ag] 2µm

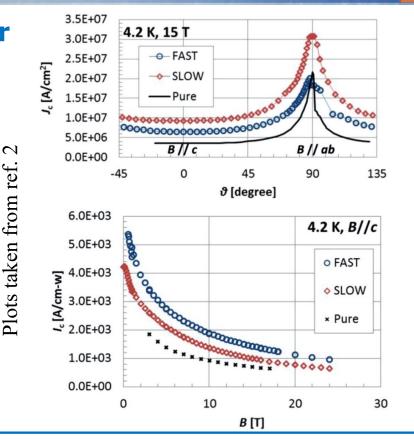
Buffer layer [MgO, etc.] 0.7µm

Sketch taken from ref. 1

Superconducting Layer

Substrate [Hastelloy®]

- **Reference Conductor** for the following analysis is the Fujikura FESC-SH12¹
 - > 12 mm wide EuBCO+BHO tape with a Hastelloy and Copper thickness respectively equal to 50 µm and 40 µm
 - \succ Measured² J_e (4.2 K)
 - $1.J_e(B_1=15 T) \sim 1.5 kA/mm^2$
 - *2.J_e*(B_{//} =15 T) ~ 4.5 kA/mm²
 - \succ Estimated I_c (4.2 K)
 - $I.I_{c}(B_{|}=50 \text{ T}) \sim 300 \text{ A}_{c}$
 - $2.I_{c}(B_{H}=50 T) > 1000 A$
 - ¹ https://www.fujikura.co.jp/eng/products/newbusiness/superconductors/01/superconductor.pdf ² Shinji Fujita, Satoshi Awaji et al. IEEE TAS, VOL. 29, NO. 5, AUGUST 2019





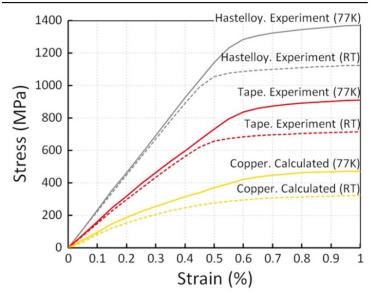
Reference Conductor for the study 2/2

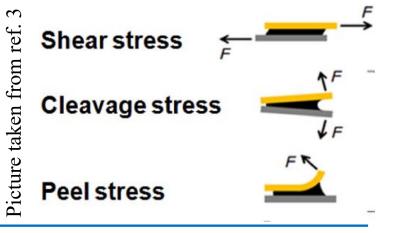


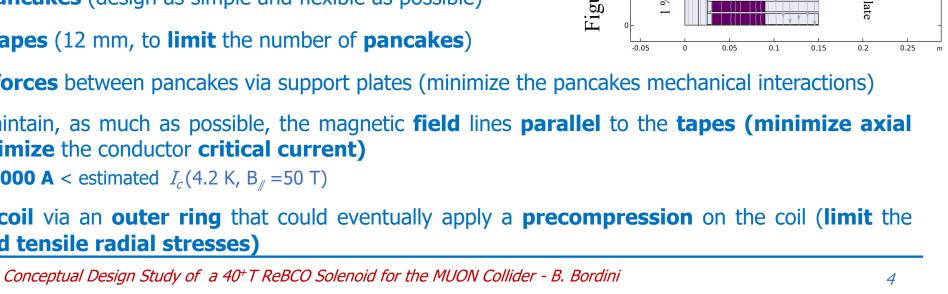
K Ilin et a

Mechanical stresses producing irreversible critical current *I_c* reduction

- Tensile longitudinal stress > 600 MPa¹ (this number can be substantially increased by reducing the copper thickness, Hastelloy deforms plastically at tensile stresses above 1000 MPa²)
- Compressive stress in thickness direction > 400 MPa¹
- Compressive stress in width direction > 100 MPa¹
- >Tensile stress in thickness direction: 10-100 MPa³
- Shear stress > 19 MPa³
- Cleavage/Peel stress³ (tensile at tape extremities)<1 MPa³
- ¹ https://www.fujikura.co.jp/eng/products/newbusiness/superconductors/01/superconductor.pdf
- ² K Ilin et al 2015 Supercond. Sci. Technol. **28** 055006
- ³ Hideaki Maeda and Yoshinori Yanagisawa IEEE TAS, VOL. 24, NO. 3, JUNE 2014





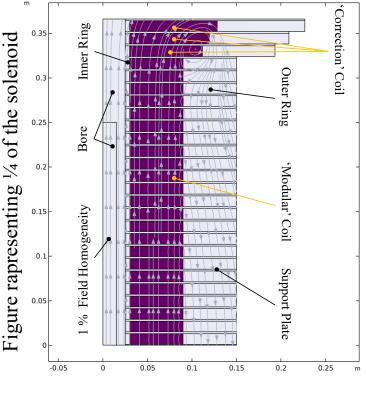


- **Principles** guiding this conceptual design **study** (based on a ٠ stationary analysis - dynamic studies to be performed at a later time)
 - > **non-insulated coils** (protection, mechanical robustness)
 - **avoid tensile radial stresses** (minimize the risk of critical current degradation)
 - **modular single layer pancakes** (design as simple and flexible as possible)
 - use as wide as possible tapes (12 mm, to limit the number of pancakes)
 - **intercept axial** Lorentz **forces** between pancakes via support plates (minimize the pancakes mechanical interactions)
 - In the 'modular' coils, maintain, as much as possible, the magnetic **field** lines **parallel** to the **tapes (minimize axial**) \succ Lorentz forces and maximize the conductor critical current)
 - **1.** current per tape < **1000 A** < estimated I_c (4.2 K, B_{\parallel} = 50 T)

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Radially support each coil via an outer ring that could eventually apply a precompression on the coil (limit the hoop stress and to avoid tensile radial stresses)

- Main Specs & Principles guiding the design study
- Main **Specs**: 1) **bore field > 40 T;** 2) **aperture 50 mm;** ۲ 3) magnetic field homogeneity 1 % over 0.5 m

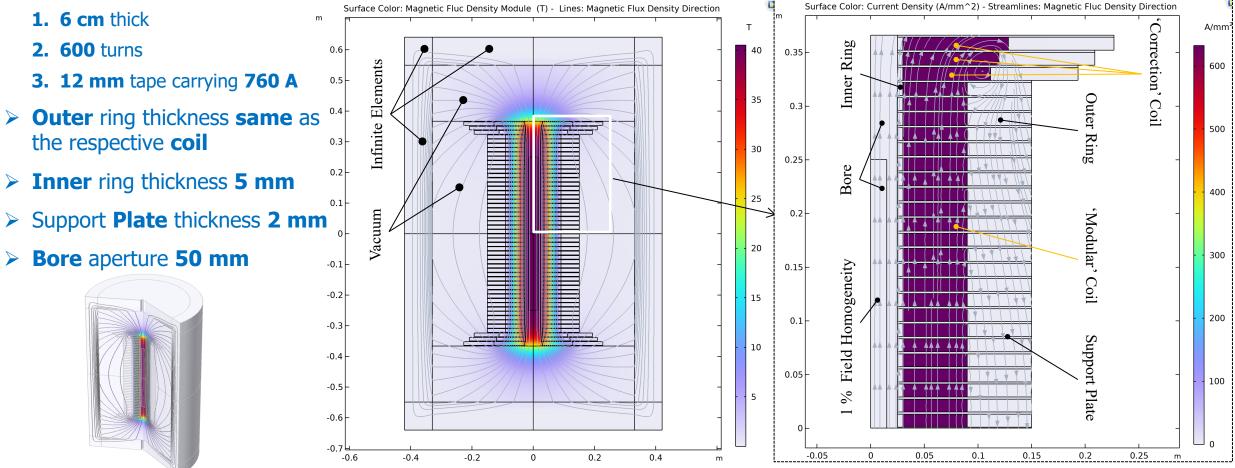




Reference Solenoid Magnetic Field and Current Density Distribution



- 46 identical 'modular' pancakes and 6 'correction' pancakes
 - Coil of the 'modular' pancake:





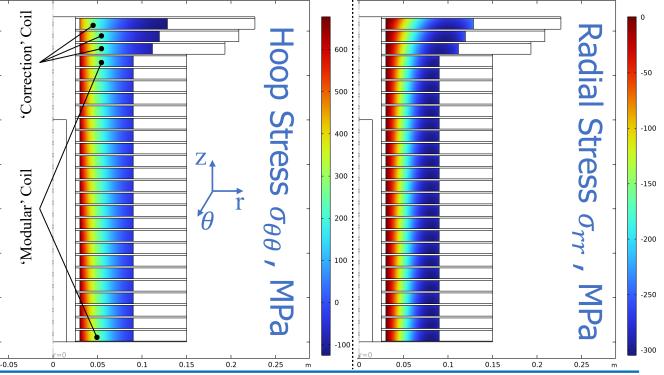
Reference Solenoid Mechanical Stresses in the Coils



- Max hoop stress ($\sigma_{\theta\theta}$) < 700 MPa and no tensile radial stress ($\sigma_{rr} \leq 0$)
- Outer ring in stainless steel applying a radial precompression of 200 MPa on the coil
- A stiffer material for the outer ring or a reduction of the tape copper content (now ~40%) would further reduce the hoop stress and the risk of having tensile radial stress

0.25

- Coil young modulus: 150 GPa (isotropic) 0.35
- Compressive stress in thickness direction < 300 MPa
- **Compressive** stress in **width** (z) **direction**
 - $\succ -\sigma_{zz}$ < 80 MPa in the 6 correction coils
 - $> -\sigma_{zz} < 15 \text{ MPa in the modular coils (assuming on the support plate intercepting the whole axial force between two adjacent coils)$
- Shear stress (σ_{rz}) < 5 MPa





200 MPa Precompression Hoop Stress vs Coil Thickness

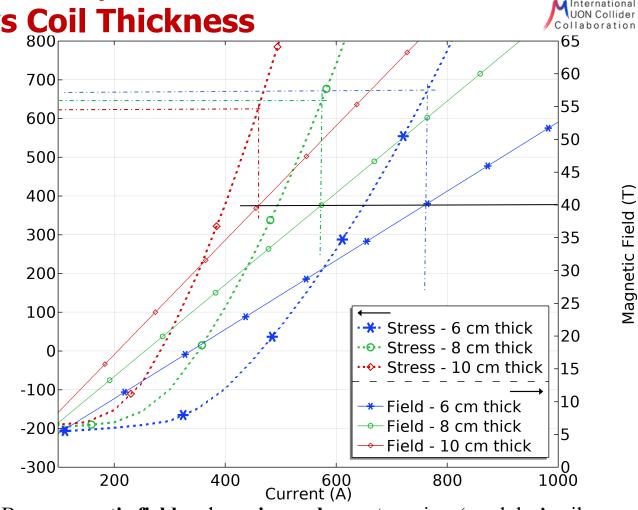
(MPa)

Stress



- At **50 T** the **hoop stress** largely **exceed** the **limit** of the conductor
- For a **single layer** pancake, **40 T** seems a reasonably **achievable target**

	Pancake thickness		
	10 cm	8 cm	6 <i>cm</i> (Ref.)
Current (A) to reach 40 T	461	574	760
Current (A) to reach 50 T	580	720	950



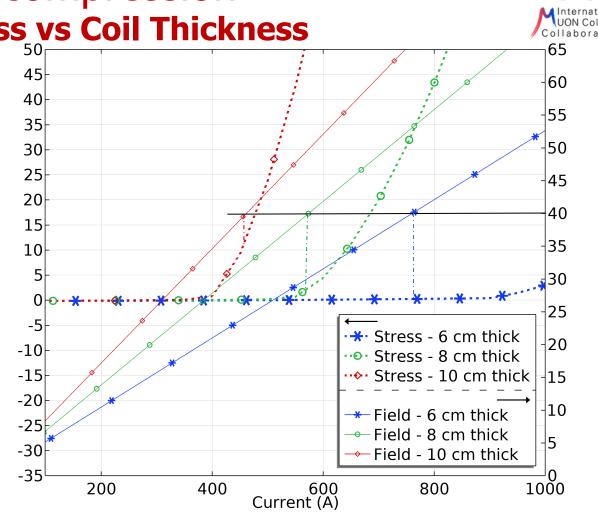
Bore magnetic field and maximum hoop stress in a 'modular' coil as a function of the tape current for different coil thicknesses.
The coil is constrained by a stainless-steel outer ring that has the same thickness as the coil and applies 200 MPa of radial pre-compression



Stress (MPa)

- The maximum radial stress (σ_{rr}) in a 'modular' coil of a 40⁺ T solenoid, increases with the coil thickness
- For a 40 T solenoid, if the coil thickness is 8 cm or larger, a tensile radial stress appears (σ_{rr} > 0) and that could cause conductor degradation
- A 6 cm thick coil guarantees a sufficient margin to prevent the occurrence of tensile radial stress for a 40 T solenoid

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Magnetic Field (T)





	Coil thickness			
	10 cm	8 cm	6 cm (Reference Solenoid)	
Max Sustainable Current ¹ (radial tensile stress < 1 MPa)	400 A	550 A	930 A	
I and J in the tape	$400 A - 391 A/mm^2$	$550 A - 457 A/mm^2$	$760 A - 632 A/mm^2$	
Magnetic Field in the solenoid	34.6 <i>T</i>	38.3 T	40 <i>T</i>	
Max radial compression ¹	250 MPa	275 MPa	300 MPa	
Max tensile hoop stress ¹	378 <i>MPa</i>	559 <i>MPa</i>	660 MPa	
Pancake Inductance single tape conductor ²	1.22 <i>H</i>	0.62 <i>H</i>	0.27 <i>H</i>	
Magnetic Energy x Pancake	98 kJ	93 kJ	77 kJ	
Tape length x coil	503 m	352 m	226 m	
Energy density in the coil ³	170 <i>J/cm</i> ³	230 <i>J/cm</i> ³	300 <i>J/cm</i> ³	

¹Assuming a 200 MPa radial precompression imposed by a stainless-steel outer ring that has the same thickness as the coil

² The inductance would be ¹/₄ of the reported one in the case of a double tape conductor

³ For reference: the variation of enthalpy from 4.2 K to 195 K for the copper is about 370 *J/cm*³



Conclusions



• CERN started to investigate the possibility of developing a 40⁺ T solenoid (fully based on ReBCO) for the Muon Collider and to get a 'feel' for what the limits are

> The critical current seems not to be a limiting factor for a 40-50 T solenoid

The electro-mechanical design will play a decisive role because the stresses on the conductor are very large

Considering the electro-mechanical behavior in stationary conditions, 40 T appears a reasonably achievable target for the proposed design while larger fields would most likely require double layers pancakes, which would increase the design complexity

Much work to be done but the mission does not look impossible, and a success would be extremely beneficial for the community